



# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**

**[List multiple models if applicable.]**

HP ProDisplay P201 20-inch LED Backlit Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		21
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		3
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	
Description #2 Hexagonal nut screw driver for DVI and D-SUB connector	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Dismantle the screws of stand, get down the stand
2. Dismantle the screws of rear cover,
3. Dismantle the rear cover of monitor
4. Tear out all tapes. Remove the screws and disconnect the connectors to separate the MAINFRAME and PANEL
5. Remove the screws and disconnect the connectors.
6. Remove the MAIN BOARD and POWER BOARD
- 7.
- 8.
- 9.
- 10.

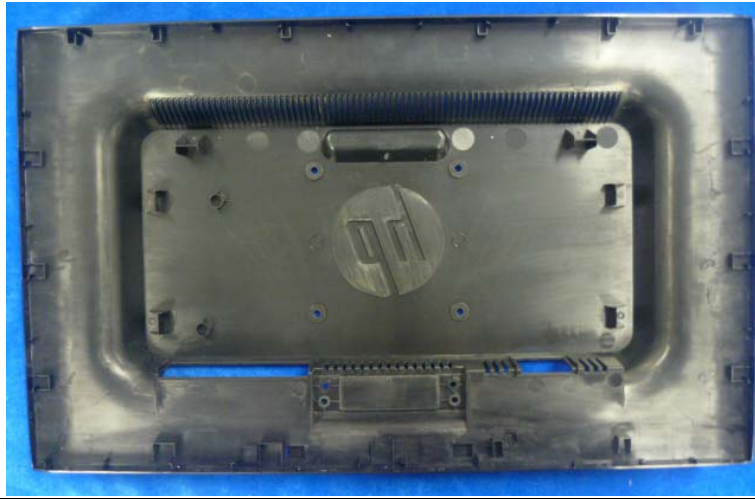
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pls. refer the attached:

## Mechanical Instructions

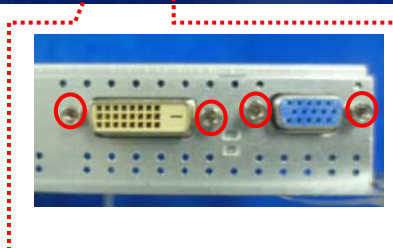
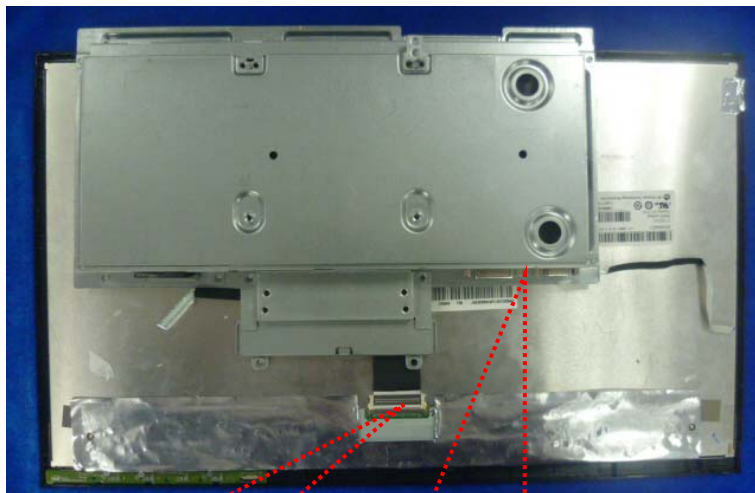
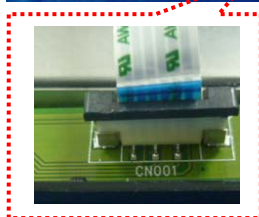
Step	Figure	Description
Preparation		The monitor
Remove the HINGE ASS'Y		Remove the screws to remove the HINGE ASS'Y.
The HINGE ASS'Y		The HINGE ASS'Y

Remove the  
REAR\_COVER



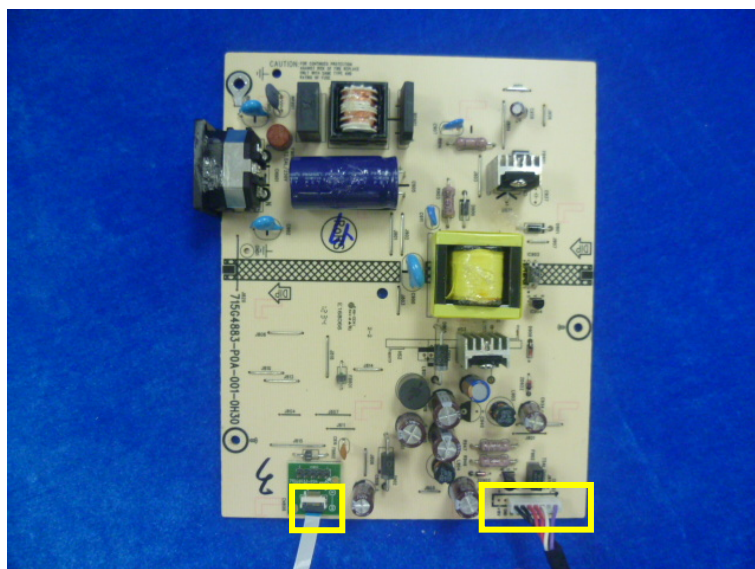
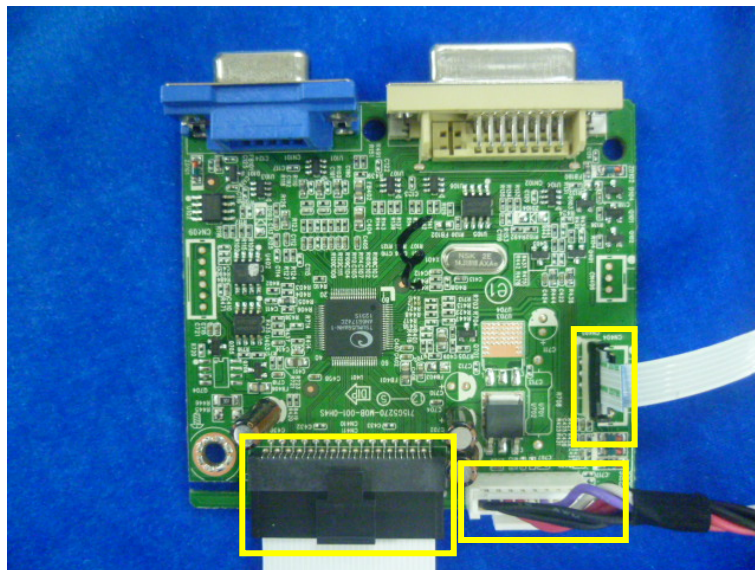
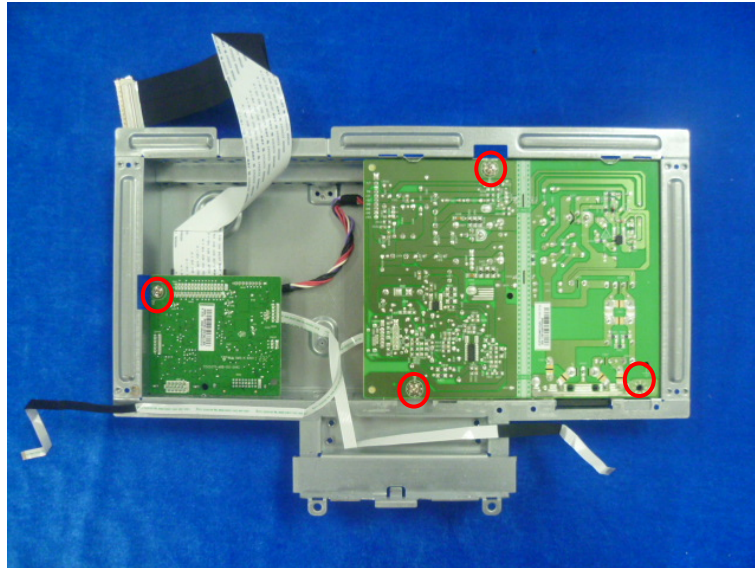
Remove the  
REAR\_COVER

Separate the  
MAINFRAME  
and PANEL

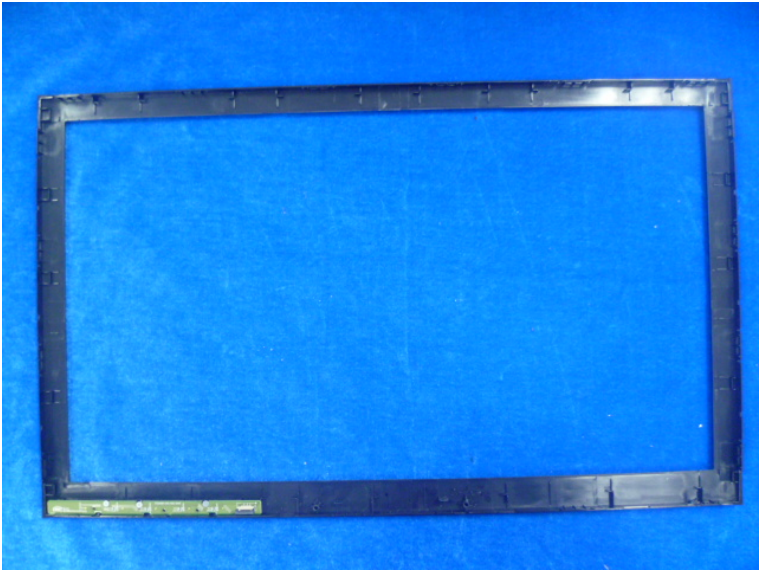



Tear out all  
tapes.  
Remove the  
screws and  
disconnect the  
connectors  
to separate the  
MAINFRAME  
and PANEL.

**Remove the  
MAIN BOARD  
and POWER  
BOARD**



Remove the  
screws and  
disconnect the  
connectors to  
remove the  
MAIN BOARD  
and POWER  
BOARD.

<p>The bezel</p>		<p>The bezel</p>
<p>The panel</p>		<p>The panel</p>